

For Immediate Release

STATS ChipPAC Achieves Major Milestone of Over 35 Million eWLB Units Shipped

***Technology and Manufacturing Production Gaining Strong
Momentum with 35 Million eWLB Units Shipped; Signals Evolution of
Wafer-Level Package Solutions***

Singapore – 8/31/2010, United States – 8/30/2010 – STATS ChipPAC Ltd. (“STATS ChipPAC” or the “Company” – SGX-ST: STATSchP), a leading semiconductor test and advanced packaging service provider, today announced it has achieved a major industry milestone in the volume ramp of embedded Wafer-Level Ball Grid Array (eWLB) technology with more than 35 million units shipped.

eWLB is an innovative technology that offers a high performance, power efficient semiconductor solution for the wireless and consumer markets. Through a combination of traditional ‘front-end’ and ‘back-end’ semiconductor manufacturing techniques with parallel processing of all the chips on the wafer, eWLB delivers a higher integration level and greater number of contact elements at a reduced manufacturing cost as compared to other packaging technology available today.

“Our record ramp of eWLB is significant because it indicates this technology is quickly gaining acceptance as the package of choice for mobile applications. Our strong commitment and razor-sharp focus on delivering the most cost effective eWLB packaging solution to the market is clearly being well received by customers,” said Wan Choong Hoe, Executive Vice President and Chief Operating Officer, STATS ChipPAC. “We believe eWLB offers significant benefits to our customers and will continue to expand the number of highly integrated wafer-level packages manufactured with eWLB technology.”

STATS ChipPAC recently introduced 300mm eWLB wafer manufacturing capabilities which will increase the available capacity with significant cost and productivity advantages. The Company is actively developing next generation eWLB technology to enable larger package sizes, higher Input/Output (I/O) density and 3D Package on Package (PoP) solutions to address a wider application market.

Forward-Looking Statements

Certain statements in this release are forward-looking statements that involve a number of risks and uncertainties that could cause actual events or results to differ materially from those described in this release. Factors that could cause actual results to differ include, but are not limited to, general business and economic conditions and the state of the semiconductor industry; prevailing market conditions; demand for end-use applications products such as communications equipment, consumer and multi-applications and personal computers; decisions by customers to discontinue outsourcing of test and packaging services; level of competition; our reliance on a small group of principal customers; our continued success in technological innovations; pricing pressures, including declines in average selling prices; intellectual property rights disputes and litigation; our ability to control operating expenses; our substantial level of indebtedness and access to credit markets; potential impairment charges; availability of financing; changes in our product mix; our capacity utilization; delays in acquiring or installing new equipment; limitations imposed by our financing arrangements which may limit our ability to maintain and grow our business;



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returns from research and development investments; changes in customer order patterns; shortages in supply of key components; customer credit risks; disruption of our operations; loss of key management or other personnel; defects or malfunctions in our testing equipment or packages; rescheduling or cancelling of customer orders; adverse tax and other financial consequences if the taxing authorities do not agree with our interpretation of the applicable tax laws; classification of our Company as a passive foreign investment company; our ability to develop and protect our intellectual property; changes in environmental laws and regulations; exchange rate fluctuations; regulatory approvals for further investments in our subsidiaries; majority ownership by Temasek Holdings (Private) Limited ("Temasek") that may result in conflicting interests with Temasek and our affiliates; unsuccessful acquisitions and investments in other companies and businesses; labor union problems in South Korea; uncertainties of conducting business in China and changes in laws, currency policy and political instability in other countries in Asia; natural calamities and disasters, including outbreaks of epidemics and communicable diseases, the continued trading and listing of our ordinary shares on the Singapore Exchange Securities Trading Limited ("SGX-ST"); and other risks described from time to time in the Company's filings with the U.S. Securities and Exchange Commission, including its annual report on Form 20-F dated March 5, 2010. You should not unduly rely on such statements. We do not intend, and do not assume any obligation, to update any forward-looking statements to reflect subsequent events or circumstances.

About STATS ChipPAC Ltd.

STATS ChipPAC Ltd. is a leading service provider of semiconductor packaging design, assembly, test and distribution solutions in diverse end market applications including communications, digital consumer and computing. With global headquarters in Singapore, STATS ChipPAC has design, research and development, manufacturing or customer support offices in 10 different countries. STATS ChipPAC is listed on the SGX-ST. Further information is available at www.statschippac.com. Information contained in this website does not constitute a part of this release.

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